Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: http://www.renesas.com

April 1st, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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RENESAS

MOS FIELD EFFECT TRANSISTOR **2SK2461**

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

DESCRIPTION

The 2SK2461 is N-Channel MOS Field Effect Transistor designed for high speed switching applications.

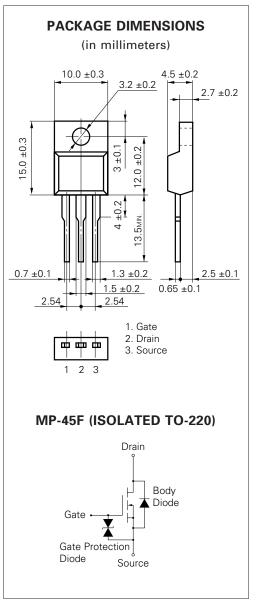
FEATURES

- Low On-Resistance R_{DS(on)1} = 80 mΩ MAX. (@ V_{GS} = 10 V, I_D = 10 A) R_{DS(on)2} = 0.1 Ω MAX. (@ V_{GS} = 4 V, I_D = 10 A)
- Low Ciss Ciss = 1400 pF TYP.
- Built-in G-S Gate Protection Diodes
- High Avalanche Capability Ratings

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

Drain to Source Voltage	Vdss	100	V
Gate to Source Voltage	Vgss	±20	V
Drain Current (DC)	D(DC)	±20	А
Drain Current (pulse)*	D(pulse)	±80	А
Total Power Dissipation (T _c = 25 $^{\circ}$ C)	Ρ τ1	35	W
Total Power Dissipation (T _A = 25 $^{\circ}$ C)	Ρτ2	2.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	–55 to +150	°C
Single Avalanche Current**	las	20	А
Single Avalanche Energy**	Eas	40	mJ
* PW \leq 10 μ s, Duty Cycle \leq 1 %			

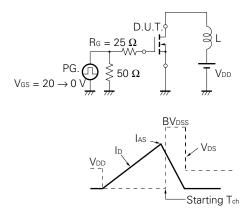
** Starting T_{ch} = 25 °C, R_G = 25 Ω , V_{Gs} = 20 V \rightarrow 0



ELECTRICAL CHARACTERISTICS (TA = 25 °C)

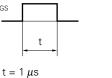
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source On-Resistance	RDS(on)1		58	80	mΩ	$V_{GS} = 10 \text{ V}, \text{ Id} = 10 \text{ A}$
Drain to Source On-Resistance	RDS(on)2		70	100	mΩ	$V_{GS} = 4 V, I_{D} = 10 A$
Gate to Source Cutoff Voltage	V _{GS} (off)	1.0	1.7	2.0	V	$V_{DS} = 10 V, I_{D} = 1 mA$
Forward Transfer Admittance	y _{fs}	12	19		S	$V_{DS} = 10 V, I_{D} = 10 A$
Drain Leakage Current	loss			10	μΑ	$V_{DS} = 100 V, V_{GS} = 0$
Gate to Source Leakage Current	lgss			±10	μΑ	$V_{GS} = \pm 20 \text{ V}, \text{ V}_{DS} = 0$
Input Capacitance	Ciss		1400		pF	$V_{DS} = 10 V$
Output Capacitance	Coss		470		pF	Vgs = 0
Reverse Transfer Capacitance	Crss		150		pF	f = 1 MHz
Turn-On Delay Time	td(on)		21		ns	I _D = 10 A
Rise Time	tr		110		ns	$V_{GS(on)} = 10 V$
Turn-Off Delay Time	td(off)		140		ns	$V_{DD} = 50 V$
Fall Time	tr		110		ns	$R_G = 10 \Omega$
Total Gate Charge	Q _G		51		nC	ID = 20 A
Gate to Source Charge	Q _{GS}		4.9		nC	$V_{DD} = 80 V$
Gate to Drain Charge	Q _{GD}		15		nC	Vgs = 10 V
Body Diode Forward Voltage	VF(S-D)		1.1		V	IF = 20 A, VGS = 0
Reverse Recovery Time	trr		170		ns	IF = 20 A, VGS = 0
Reverse Recovery Charge	Qrr		770		nC	di/dt = 100 A/µs

Test Circuit 1 Avalanche Capability



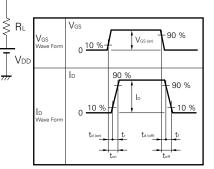
D.U.T ۸۸۸<u>--</u>c $\bigoplus_{R_G}^{VVV} R_G = 10 \Omega$ PG. V_{GS}

Test Circuit 2 Switching Time

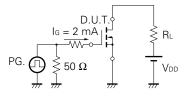


Duty Cycle ≤ 1 %

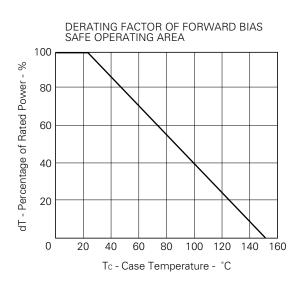
0



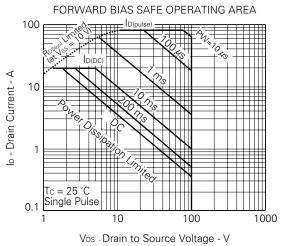
Test Circuit 3 Gate Charge



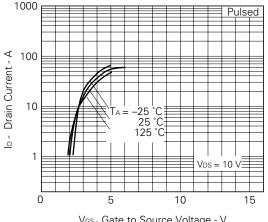
The application circuits and their parameters are for references only and are not intended for use in actual design-in's.



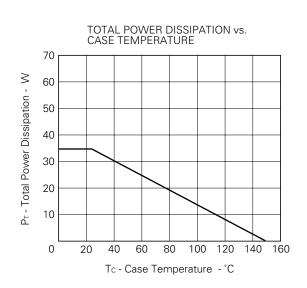




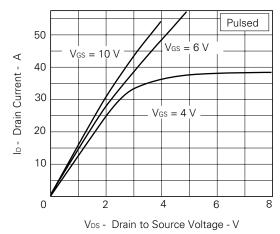


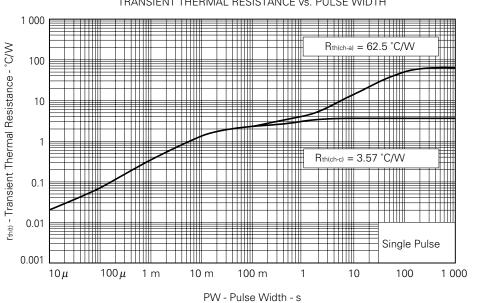






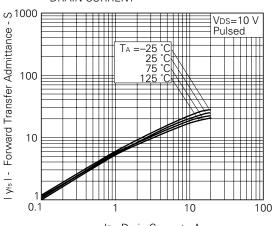
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



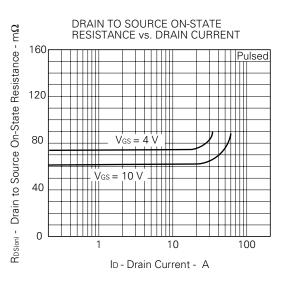


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

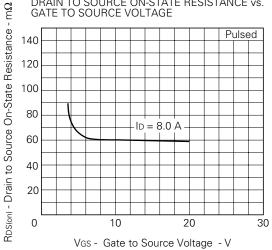




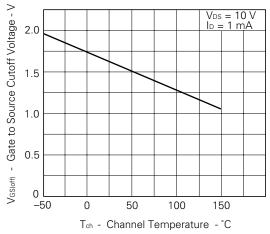




DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE



Pulsed

3.0

 $V_{\text{DD}} = 50 \text{ V}$ $V_{\text{GS}} = 10 \text{ V}$ $R_{\text{G}} = 10 \Omega$

 $V_{DD} = 80 V$ ID = 20 A

Vgs

60

100

16

14 >

12

10 8

6

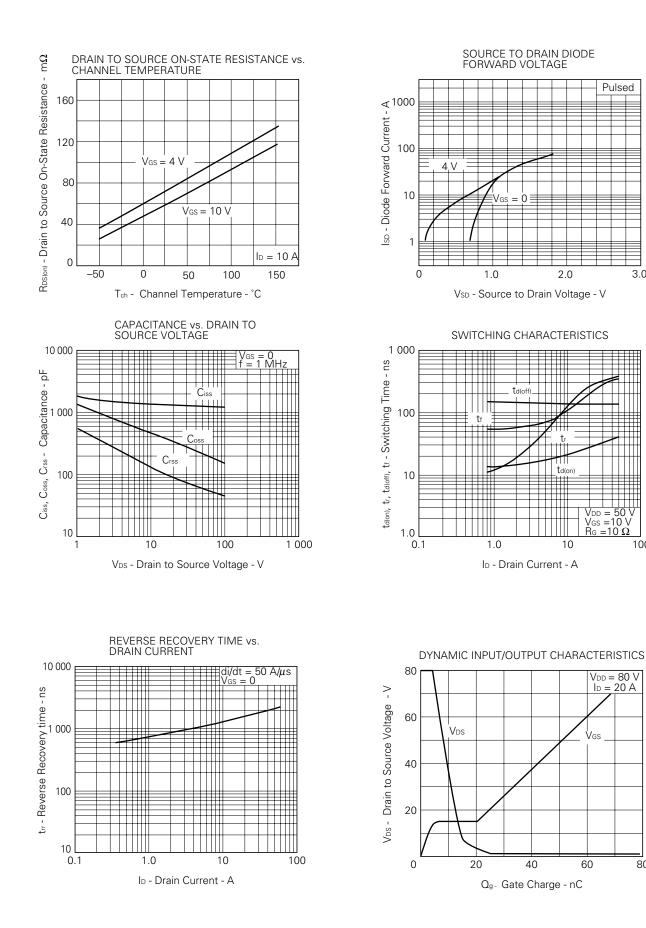
4

2

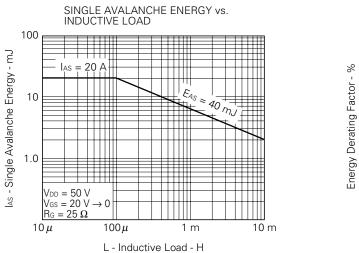
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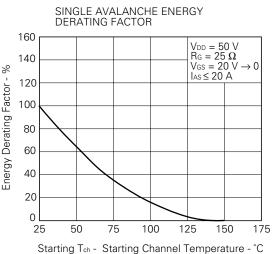
80

V_{GS} - Gate to Source Voltage -



5





REFERENCE

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134
Power MOS FET features and application switching power supply.	TEA-1034
Application circuits using Power MOS FET.	TEA-1035
Safe operating area of Power MOS FET.	TEA-1037

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device is actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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